

**AN ELECTRICAL CIRCUIT ASSEMBLY WITH IMPROVED SHOCK
RESISTANCE**

Abstract of the Invention

5 An assembly of the present invention includes a substrate and an integrated circuit device adapted to be electrically and mechanically attached to the substrate. Electrically conductive connecting elements between the device and the substrate electrically connect the device and the substrate. At least one adhesive body is positioned between the integrated circuit device and the substrate to form a mechanical connection between the circuit device and the substrate. The at least one adhesive body comprises a non-thermosetting material which, when heated, releases said mechanical connection to allow removal of the circuit device from the substrate.